

FORM PTO-1595  
(Rev. 6-93)  
OMB No. 0651-0011 (exp. 4/94)  
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To the Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

<p>1. Name of conveying party(ies):</p> <p>Hajime FUNAHASHI</p>	<p>2. Name and address of receiving party(ies):</p> <p>FUJI POLYMER INDUSTRIES CO., LTD. 21-11, Chiyoda 5-Chome, Naka-ku, Nagoya-shi Aichi 460-0012 Japan</p>
<p>Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>	<p>Additional name(s) &amp; address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>

3. Nature of conveyance:

Assignment       Merger  
 Security Agreement       Change of Name  
 Other:

Execution Date: July 30, 2010

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)      B. Patent No.(s)

12/920895

Additional numbers attached?  Yes  No

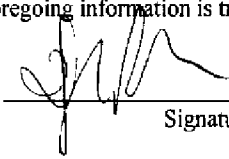
<p>5. Name and address of party to whom correspondence concerning document should be mailed:</p> <p>Name: Douglas P. Mueller Address: Hamre, Schumann, Mueller &amp; Larson P.C. P. O. Box 2902 Minneapolis, MN 55402-0902</p>	<p>6. Total number of applications and patents involved:</p> <p>7. Total fee (37 CFR 3.41): \$40.00</p> <p><input type="checkbox"/> Enclosed <input checked="" type="checkbox"/> Authorized to be charged to Deposit Account No. 50-3478.</p> <p>8. Please charge any additional fees or credit any overpayments to our Deposit account number: 50-3478</p>
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9. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Douglas P. Mueller  
Name of Person Signing

  
Signature

September 3, 2010  
Date

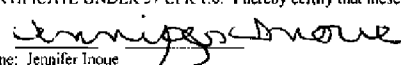
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CERTIFICATE UNDER 37 CFR 1.6. I hereby certify that these papers are being transmitted via facsimile to the U.S. Patent and Trademark Office on September 3, 2010 .

By:   
Name: Jennifer Inoue

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CH \$40.00 503478 12920895

Docket No. 10873.2431USWO

### ASSIGNMENT OF PATENT APPLICATION

WHEREAS,

1. Hajime FUNAHASHI residing at c/o Fuji Polymer Industries Co., Ltd., Aichi Factory, 175, Kajiyashiki-cho, Toyota-shi, Aichi 470-0533, JAPAN and a citizen of Japan

(hereinafter called "THE UNDERSIGNED") have made an invention and have executed an application for Letters Patent of the United States for this invention which was filed on \_\_\_\_\_, entitled THERMALLY CONDUCTIVE RESIN COMPOSITION, and which has been given application serial number \_\_\_\_\_;

and

WHEREAS Fuji Polymer Industries Co., Ltd. (hereinafter "ASSIGNEE") a corporation organized under the laws of Japan and having an office and place of business at 21-11, Chiyoda 5-chome, Naka-ku, Nagoya-shi, Aichi 460-0012, JAPAN wishes to acquire the entire right, title and interest in and to said invention and patent application and any Letters Patent to be obtained therefor;

NOW, THEREFORE, for and in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, THE UNDERSIGNED hereby sell, assign, and transfer to the ASSIGNEE, its successors, legal representative and assigns, the entire right, title and interest for the United States in and to the invention disclosed in said application, and in and to said application, as well as to all divisions, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and THE UNDERSIGNED hereby authorize and request the Commissioner of Patents of the United States to issue all Letters Patent for said invention to the ASSIGNEE of the entire right, title and interest in and to the same, in accordance with the terms of this instrument.

THE UNDERSIGNED hereby agree that THE UNDERSIGNED, their executors and legal representatives will make, execute and deliver (without charge but at the expense of the ASSIGNEE) any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said ASSIGNEE, its successors and representatives all facts known to the UNDERSIGNED relating to said invention and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable to vest the ASSIGNEE, its successors or assigns, the entire right, title and interest in and to the said invention, patent applications, Letters Patent, rights, titles, benefits, privileges, and advantages hereby sold, assigned and conveyed, or intended so to be.

THE UNDERSIGNED represent and agree with said ASSIGNEE, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the

rights and property herein conveyed has been or will be made to others by the UNDERSIGNED, and that full right to convey the same as herein expressed is possessed by the UNDERSIGNED.

IN TESTIMONY WHEREOF, THE UNDERSIGNED have hereunto set their hand on the dates indicated below.

H. Zunahashi  
Signature

July 30<sup>th</sup>, 2010  
Date